



Material Content Data Sheet



Sales Product Name		BTT6050-1EKA		Issued		24. January 2018		
MA#		MA001618314						
Package		PG-DSO-14-47		Weight*		150.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.990	1.32	1.32	13249	13249
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		461	
	non noble metal	iron	7439-89-6	1.383	0.92		9211	
wire	non noble metal	copper	7440-50-8	56.175	37.40	38.38	374006	383793
	non noble metal	copper	7440-50-8	0.483	0.32	0.32	3214	3214
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1137
encapsulation	plastics	epoxy resin	-	7.859	5.23		52325	
	inorganic material	silicondioxide	60676-86-0	77.394	51.54	56.88	515282	568744
leadfinish	non noble metal	tin	7440-31-5	2.472	1.65	1.65	16456	16456
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9789	9789
glue	plastics	epoxy resin	-	0.125	0.08		832	
	noble metal	silver	7440-22-4	0.589	0.39	0.47	3923	4755
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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